



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

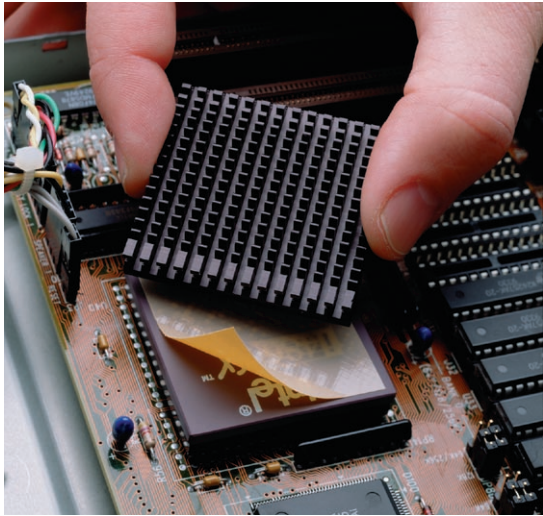
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## Thermally Conductive Material for Cooling Central Processing Units



Bergquist CPU Pad is a thermally conductive, electrically insulating, double coated tape. The tape consists of a high performance acrylic, pressure sensitive adhesive, on both sides of a film. This product can be used in applications that currently require clips. CPU Pad is typically used to mount a heat sink on top of a central processing unit on the circuit board.

### Application Force for CPU Pad

CPU Pad is a high performance, acrylic, pressure sensitive adhesive. Being pressure sensitive, the adhesive makes a strong bond to surfaces with little or no pressure. Parts can simply be assembled and placed on the CPU Pad. Immediately after placement, the parts are securely bonded together. No long clamping times or high pressures are required.

### Mounting Procedure

1. Insure cleanliness of central processing unit and heat sink.
2. Remove the clear liner from one side of the CPU Pad.
3. Roll the pad onto the substrate.
4. Remove the white liner.
5. With moderate pressure (less than 10 psi), press the part in place.

### TYPICAL PROPERTIES OF CPU Pad

PROPERTY	TYPICAL VALUE	METRIC VALUE/ 5 MIL	TYPICAL VALUE 9 MIL	TEST METHOD
Color	Tan	Tan	Tan	Visual
Thickness	.005 ±.001	.127 mm	.009 ± .001	ASTM D 374
Tensile Strength	5000 psi	35 MPa		ASTM D 412
Elongation	40 %	40 %		ASTM D 412
Glass Transition	-70 °C	-70 °C	-70 °C	TMA
<b>Adhesion</b>				
Adhesion to Aluminum	4 lbs./in	7 N/cm	2700 grams per in.	ASTM D 1876
Adhesion to Liner	16 g/inch	6 N/m	50 gr. grams per in.	ASTM D 1876
Tensile Shear	120 psi	.84 MPa	140 psi	ASTM D 1002
<b>Thermal Properties</b>				
Thermal Conductivity	0.6 W/m-K	0.6 W/m-K	0.4 W/m-K	ASTM D5470
Thermal Resistance	0.3 C-in <sup>2</sup> /W	1.9 °Cmm <sup>2</sup> /w	.42 °C-in <sup>2</sup> /W	ASTM D5470
Thermal Coefficient of expansion	450 ppm	450 ppm		TMA
<b>Thermal Cycling</b> 1 Hour at -50°C and 1 Hour at 150°C				
<b>Time</b>	<b>Peel Adhesion</b>	<b>Voltage Breakdown</b>		<b>Visual</b>
Cycles	PLI (N/cm)			
0	3.6 (6.4)	6000		Pass
100	3.8 (6.8)	6000		Pass
200	4.5 (8.1)	6000		Pass
300	4.7 (8.4)	6000		Pass